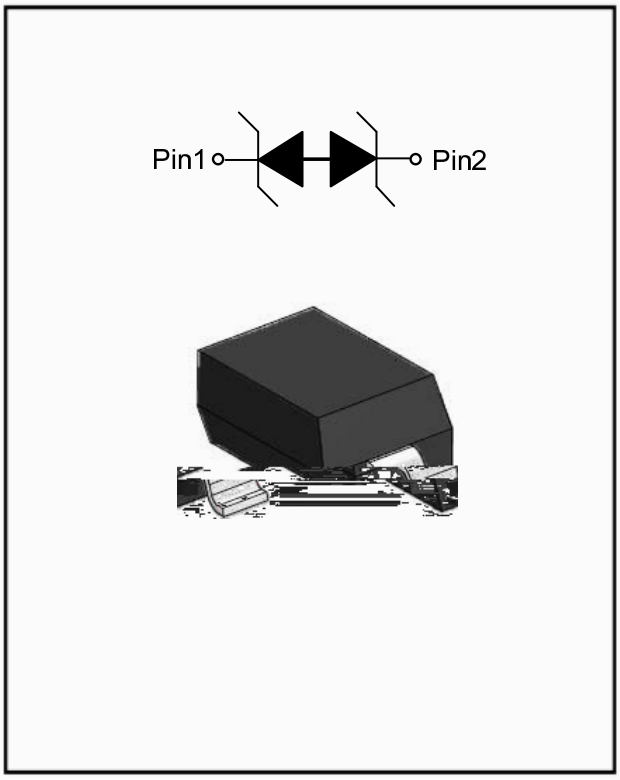


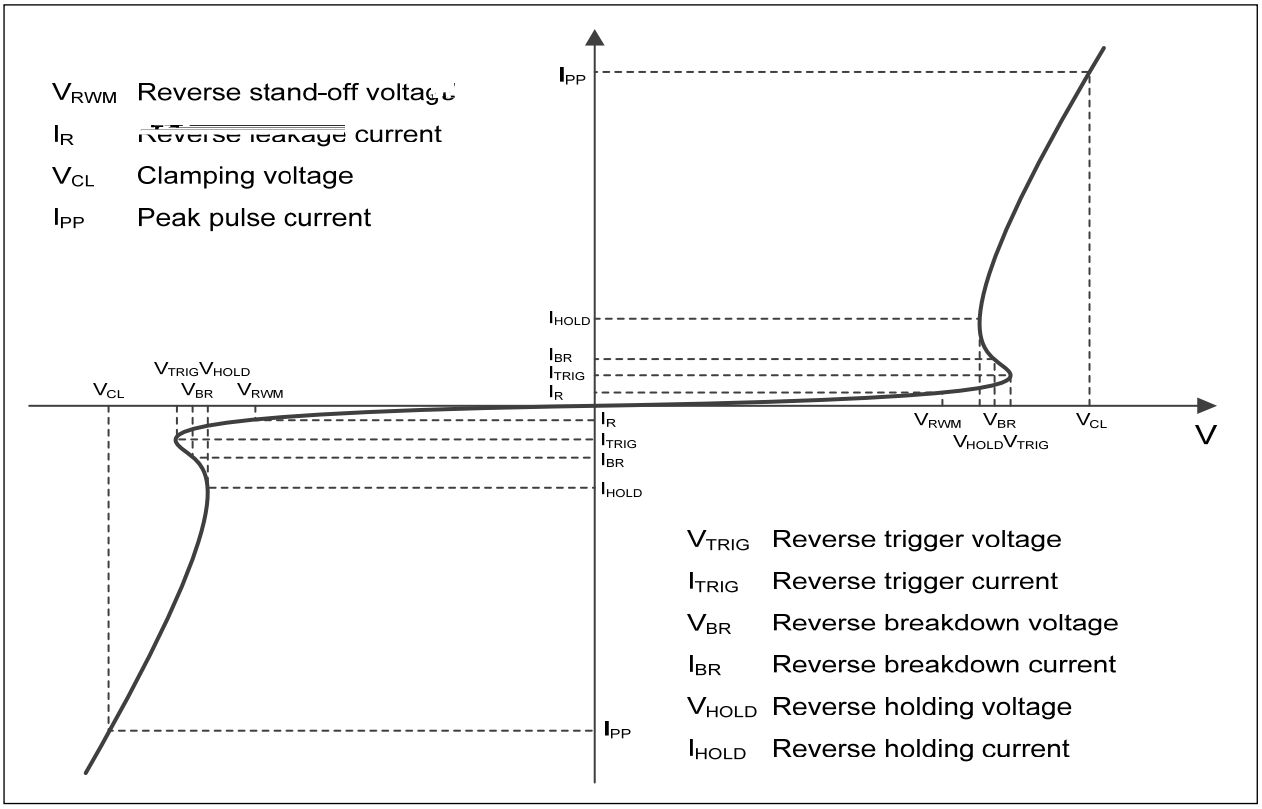
- Stand-off voltage: ±3.3V Max
- Transient protection for each line according to
IEC61000-4-2(ESD): ±30kV (contact)
IEC61000-4-5(surge): 8A (8/20μs)
- Ultra-low capacitance: CJ = 15pF typ
- Low leakage current
- Low clamping voltage:
V_{CL} =11V typ. @ IPP = 16A(TLP)

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- Audio Players
- Keypads, Side Keys, LCD Displays

- Package: SOD-323
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound.
- Moisture Sensitivity: Level 1 per J-STD-020
- Marking Information: See Below



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Peak pulse power (t_p = 8/20μs)	P_{pk}	88	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	8	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	KV
Junction temperature	T_J	125	°C
Operating temperature	T_{OP}	-40~85	°C
Storage temperature	T_{STG}	-55~150	°C

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Reverse maximum working voltage	V_{RWM}	V				±3.3
Reverse leakage current	I_R	nA	V_{RWM} =3.3V			100
Reverse breakdown voltage	V_{BR}	V	I_T = 1mA	3.6		5.0
Clamping voltage 1)	V_{CL}	V	I_{PP} = 16A, t_p = 100ns		11	
Dynamic resistance 1)	R_{DYN}	Ω			0.36	
Clamping voltage 2)	V_{CL}	V	V_{ESD} = 8kV		10	
Clamping voltage 3)	V_{CL}	V	I_{PP} = 1A, t_p = 8/20μs			8
		V	I_{PP} = 8A, t_p = 8/20μs			11
Junction capacitance	C_J	pF	V_R = 0V, f = 1MHz		15	
		pF	V_R = 2.5V, f = 1MHz		12	

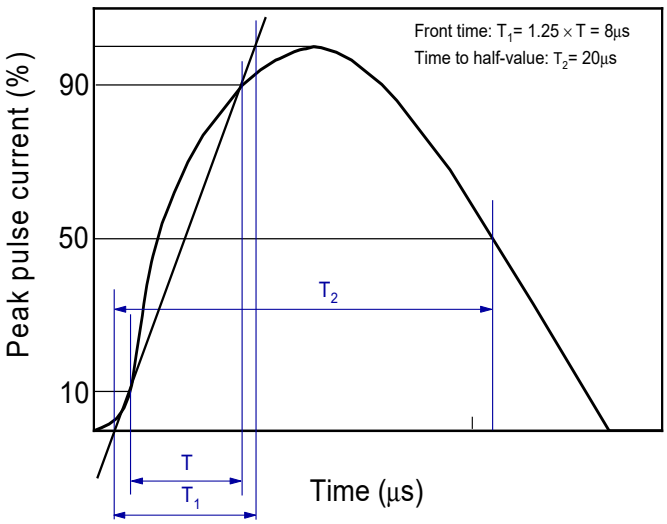
(1). TLP parameter: Z_0 = 50Ω, t_p = 100ns, t_r = 2ns, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.
(2). Contact discharge mode, according to IEC61000-4-2.
(3). Non-repetitive current pulse, according to IEC61000-4-5.

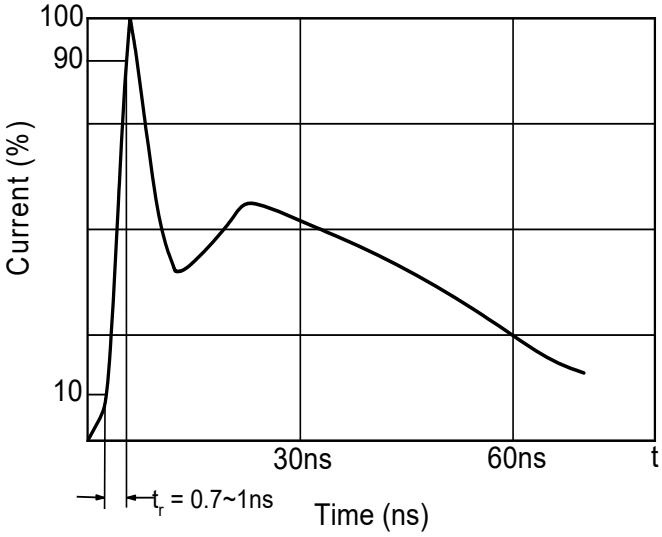
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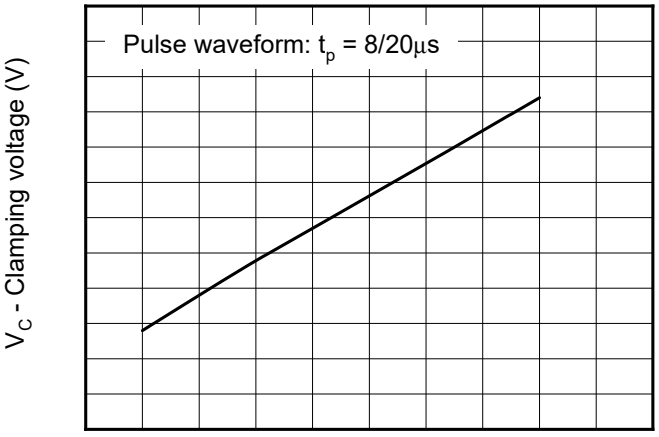
ESD3V3D3B	F2	Approximate 4	3000	30000	120000	7” reel

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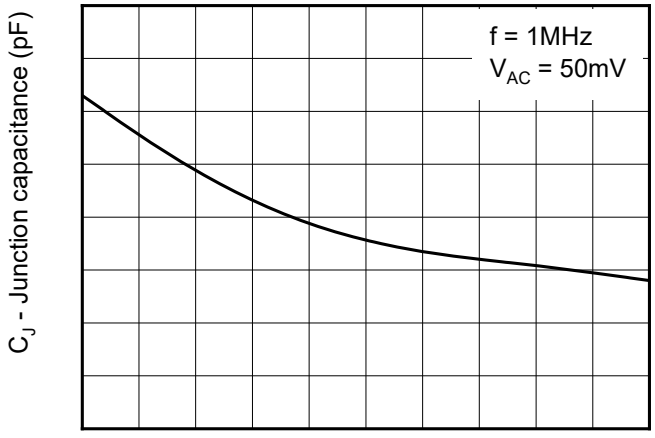
μ



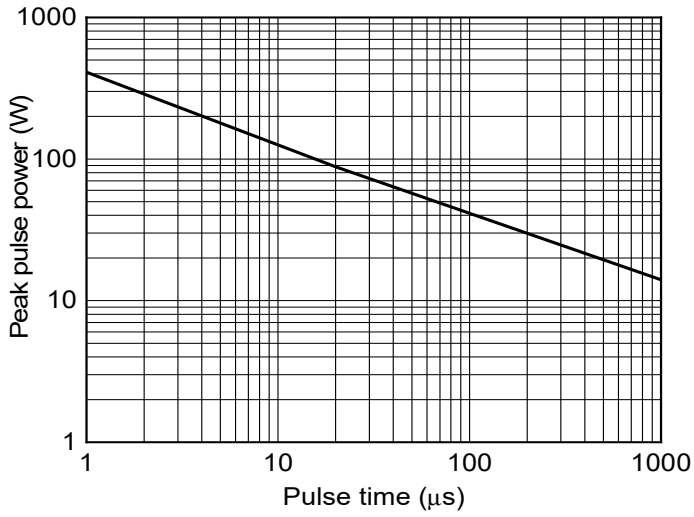


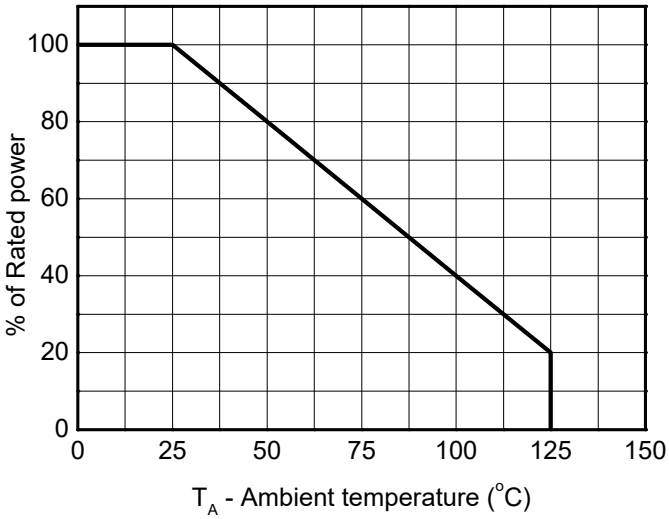


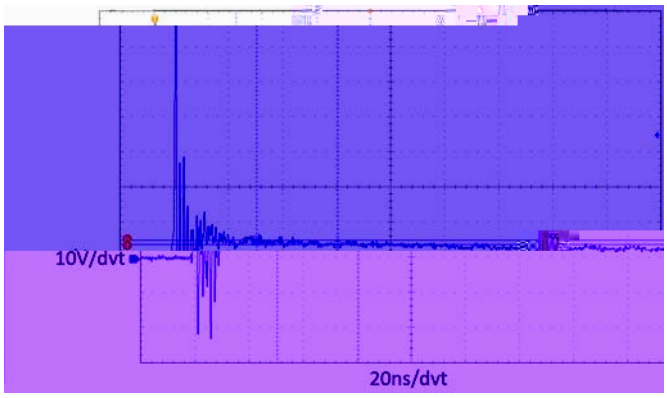
I_{PP} - Peak pulse current (A)

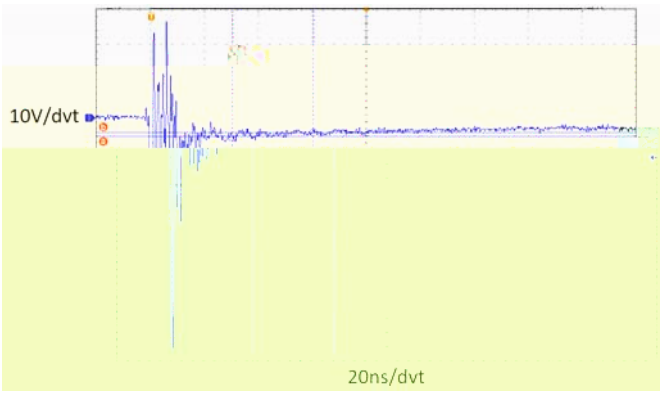


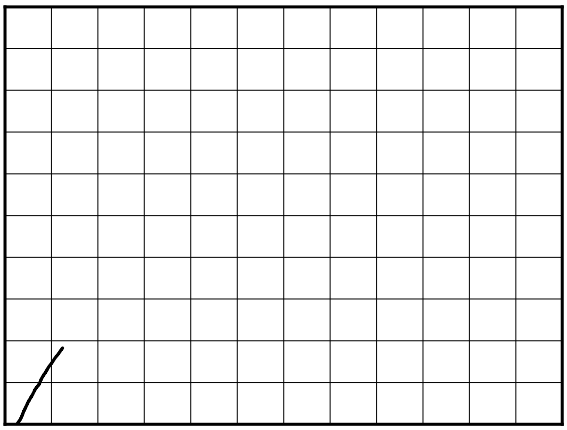
V_R - Reverse voltage (V)











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Notes:
This suggested land pad layout is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met